

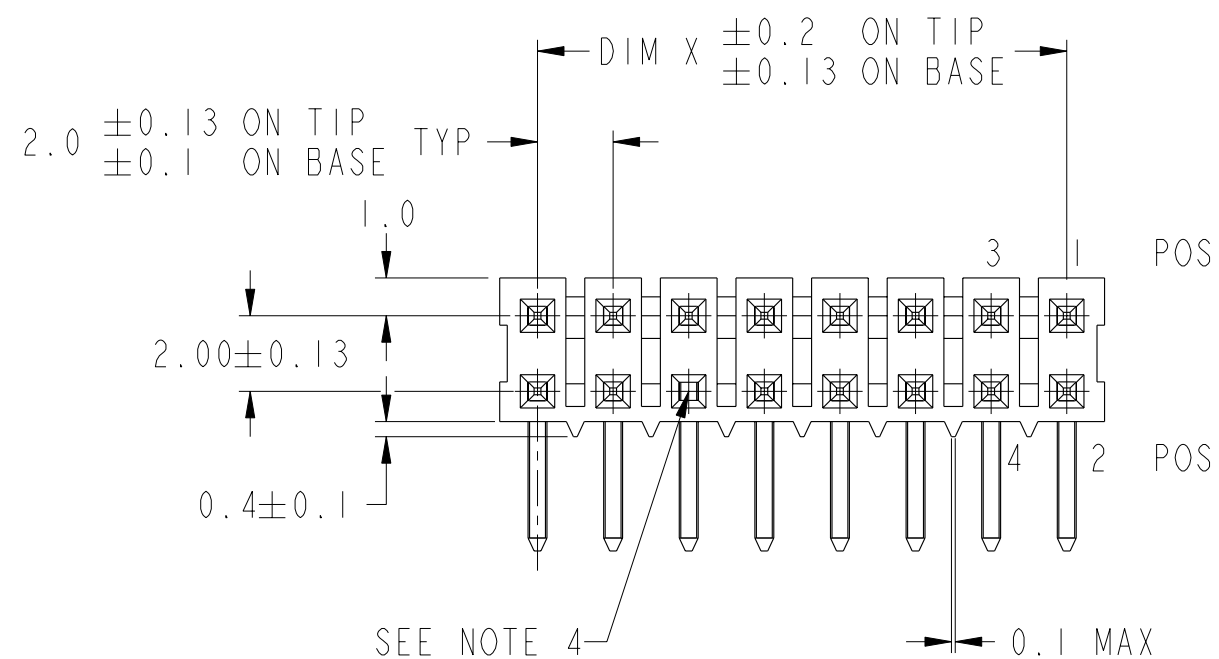
1

2

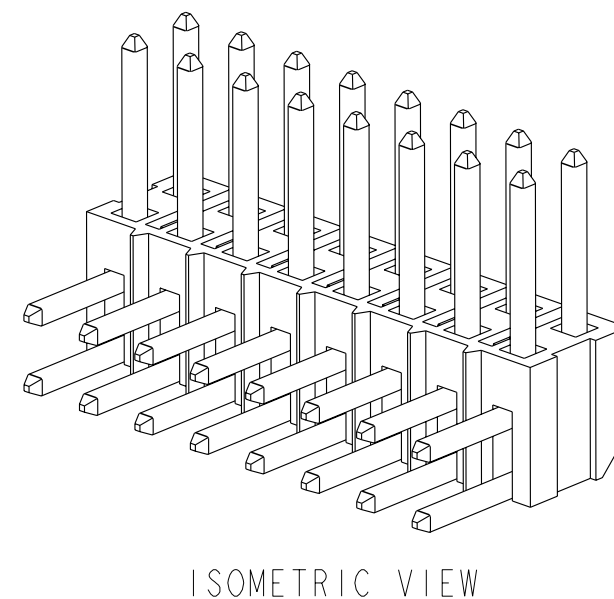
3

4

A



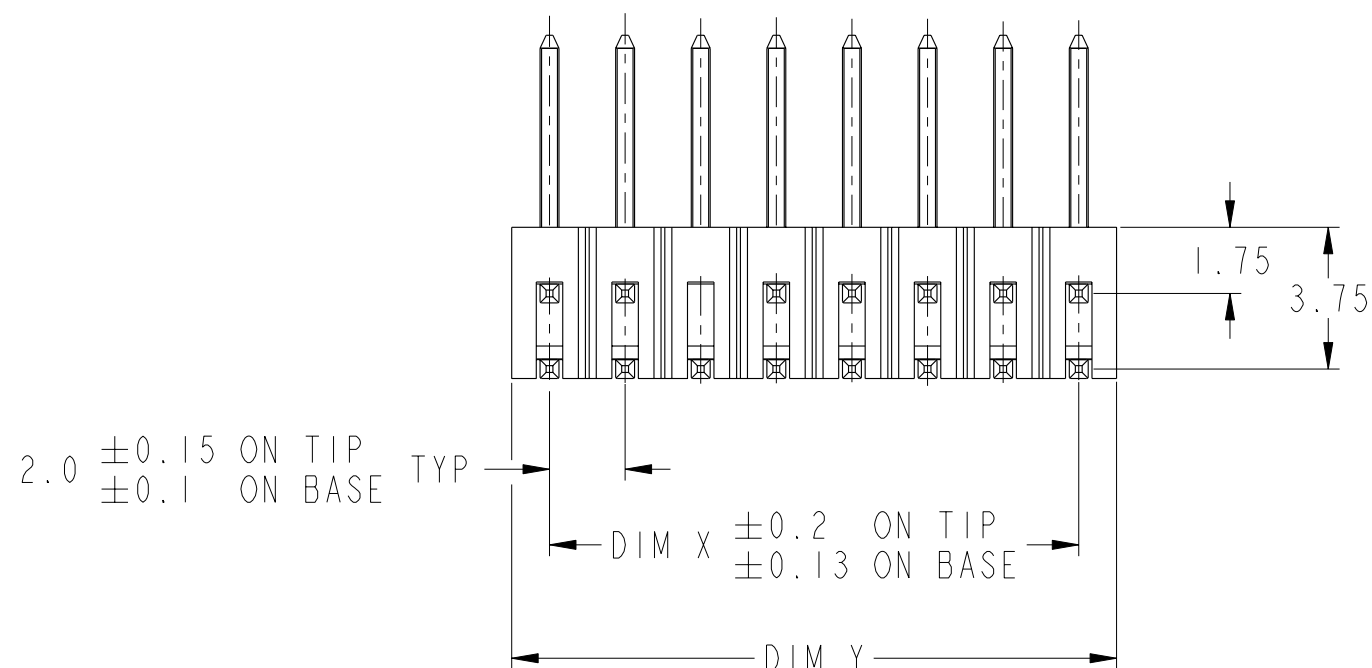
B



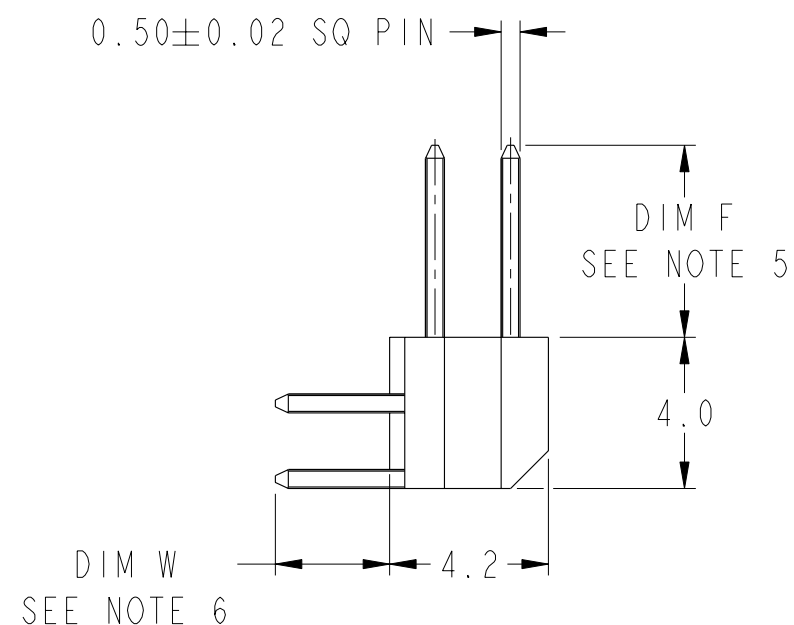
A

B

C



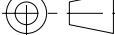
D



C

D

CONFIDENTIAL

www.fciconnect.com			surface ISO 1302		- ✓ tolerance std ISO 406 ISO 1101		projection 		MM 	
			TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	BS LOW	1998-07-29	ANGULAR		LINEAR		X.X	±-	size A3	Scale 5:1
Eng	JPEH	2002-12-19					X.XX	±0.25		
Chr	KH LEE	2010-02-04	0°	±°			X.XXX	±-	ECN	S10-0205
Appr	JOEY NG	2010-02-04	Product family				MINITEK	Spec ref -		
			title MINITEX II POL. R/A HEADER (SnPb S.T)				dwg no 63411			Rev E
			catalog no -				CUSTOMER		sheet 1 of 2	

1

2

3

PDM: Rev:E

STATUS: Released

Printed: Dec 21, 2010

PRODUCT NO	POS	POL.POS	DIM X	DIM Y	DIM "W"	DIM "F"
63411-X01	2 X 3	3	4	6	2.5	4.0
63411-X02	2 X 8	--	14	16	3.0	5.08

NOTES

1. MATERIAL

BODY : HIGH TEMPERATURE PLASTIC UL 94V-0 BLACK
PIN : COPPER ALLOY

2. TOLERANCE UNLESS OTHERWISE NOTED ± 0.25

3. STAND-OFF DESIGN FOR 2X2 POS.(FIG. 1).

4. POLARISED BY OMISSION OF PINS.
REFER TABLE FOR POSITION.

5. PLATING ON MATING LENGTH:

- 1XX --- $0.76\mu\text{m}$ Au OVER $1.27\mu\text{m}$ MIN Ni UNDERPLATE.
- 3XX --- $0.38\mu\text{m}$ Au OVER $1.27\mu\text{m}$ MIN Ni UNDERPLATE.
- 5XX --- $0.38\mu\text{m}$ PdNi WITH Au FLASH OVER $1.27\mu\text{m}$ MIN Ni UNDERPLATE.
- 6XX --- $0.76\mu\text{m}$ PdNi WITH Au FLASH OVER $1.27\mu\text{m}$ MIN Ni UNDERPLATE.

6. SOLDER TAIL PLATING:

- a) $3.81\mu\text{m}$ MIN TIN/LEAD PLATING OVER $1.27\mu\text{m}$ MIN NICKEL UNDERPLATE FOR P/N: 63411-XXX.
- b) $2.54\mu\text{m}$ MIN 100% MATTE TIN PLATING OVER $1.27\mu\text{m}$ MIN NICKEL UNDERPLATE FOR P/N: 63411-XXXLF.

7. STANDARD PACKAGING : POLY BAG

8. PRODUCT DESCRIPTION CODE:

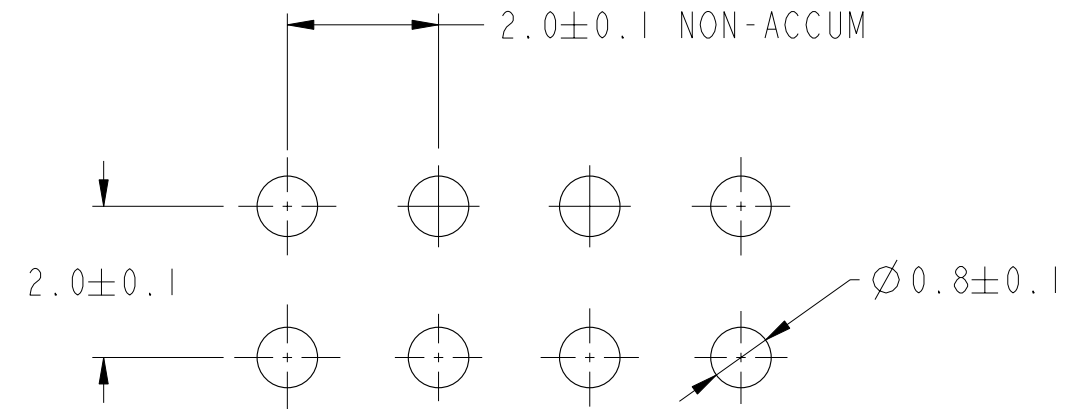
XXXXX-XXXLF

LEAD FREE (SEE NOTES 6b & 11)

EXTENSION NUMBER

BASE NUMBER

9. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.



RECOMMENDED PCB HOLE LAYOUT

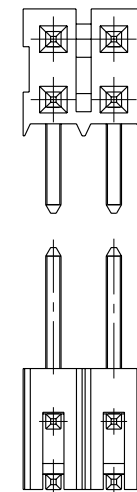


FIG. 1

SEE NOTE 3

10. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.

11. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

12. A $\triangle E$ SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

CONFIDENTIAL

www.fciconnect.com			surface ISO 1302	tolerance std ISO 406 ISO 1101	projection size A3	MM Scale 5:1
			TOLERANCES UNLESS OTHERWISE SPECIFIED			
Dr	BS LOW	1998-07-29	ANGULAR 0° ±°	LINEAR	x.x	±-
Eng	JPEH	2002-12-19			x.xx	±0.25
Chr	KH LEE	2010-02-04			x.xxx	±-
Appr	JOEY NG	2010-02-04	Product family			ECN S10-0205
			MINITEK			Spec ref -
FCI			MINITEX II			Rev.
			POL. R/A HEADER (SnPb S.T.)			E
			catalog no			
			CUSTOMER			sheet 2 of 2